

**REMARKS**

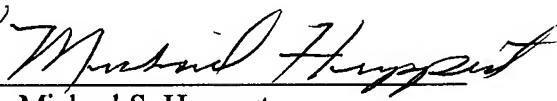
The present Preliminary Amendment is submitted to complete the reference to the parent application on page 1 of the specification.

A copy of the amended portion of the specification with changes marked therein is attached and entitled "Version with Markings to Show Changes Made."

Note, a petition for a two month extension of time has been filed in the parent application No. 09/010,490 to maintain co-pendency with the present CIP application.

Respectfully submitted,

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February 22, 2002

## COMPONENT MOUNTING APPARATUS AND METHOD

### CROSS REFERENCE OF RELATED APPLICATIONS

[0001] This application is a continuation-in-part of copending application serial number 09/010,490, filed January 21, 1998, which is a continuation of Serial No. 08/1740,992, filed November 5, 1996, now Patent No. 5,778,525. ~~Serial No. 08/1740,992, filed November 5, 1996, now Patent No. 5,778,525.~~

### BACKGROUND OF THE INVENTION

[0002] The present invention relates to component mounting apparatus and method for automatically mounting a variety of components such as electronic components onto a printed circuit board or the like, and a component mounting equipment including the apparatuses.

[0003] Generally, in an electronic component mounting apparatus, a number of component supply means are mounted in parallel to one another on a component supply table. In a component mounting stage, the component supply means are successively positioned in a specified component supply position according to a sequence of mounting components